## MA2YD28

## Silicon epitaxial planar type

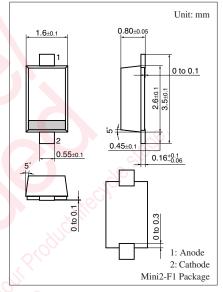
#### For high speed switching

#### ■ Features

- Forward current (Average)  $I_{F(AV)} = 1.5$  A rectification is possible
- ullet Low forward voltage  $V_F$
- Mini type 2-pin package

### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Reverse voltage	$V_R$	30	V
Repetitive peak reverse voltage	$V_{RRM}$	30	V
Forward current (Average) *1	I <sub>F(AV)</sub>	1.5	A
Non-repetitive peak forward surge current *2	I <sub>FSM</sub>	3	A
Junction temperature	$T_{j}$	150	°C
Storage temperature	$T_{stg}$	-55 to +150	°C



Marking Symbol: 2Z

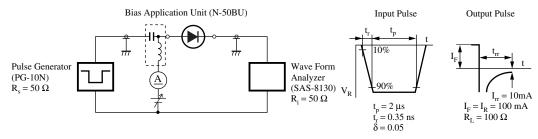
Note) \*1: Mounted on a alumina PC board

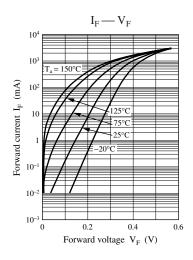
\*2: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)

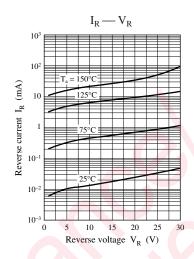
## ■ Electrical Characteristics $T_a = 25$ °C ± 3°C

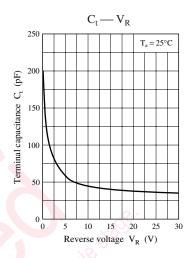
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	$V_{F1}$	$I_{\rm F} = 0.5 \; {\rm A}$		0.35	0.39	V
	$V_{F2}$	$I_F = 1.0 \text{ A}$		0.40	0.44	
	$V_{F3}$	I <sub>F</sub> = 1.5 A	5.00	0.45	0.49	
Reverse current	$I_R$	$V_R = 30 \text{ V}$			100	μΑ
Terminal capacitance	C <sub>t</sub>	$V_R = 10 \text{ V}, f = 1 \text{ MHz}$		50		pF
Reverse recovery time *	t <sub>rr</sub>	$I_F = I_R = 100 \text{ mA}$		13		ns
		$I_{rr} = 10 \text{ mA}$ , $R_L = 100 \Omega$				

- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
  - 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
  - 3. \*: t<sub>rr</sub> measurement circuit









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